

Art Unit: ***

Claims PTO

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AMW

Claims 1-16 cancelled.

17. A method of distributing power in a semiconductor device, comprising;

providing at least one pair of bond pads to the semiconductor device;

providing an input/output bond pad to the semiconductor device, the input/output bond pad to receive and input/output bond wire operable for electrically connecting to a package;

connecting a single corresponding bond wire between each of the at least one pair of bond pads such that each bond pad of each of the at least one pair of bond pads has only one bond wire end connected thereto; and

locating a first bond pad of the at least one pair of bond pads in an internal portion of the semiconductor die.

18. The method of Claim 17 further comprising locating a second bond pad the at least one pair of bond pads along a periphery of the semiconductor die.

19. The method of Claim 17 wherein the single corresponding bond wire comprises a metallic material selected from the group consisting of gold, aluminum, and copper.

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20. The method of Claim 17 further comprising bonding the single corresponding bond wire to the pair of bond pads using a wire bond type selected from the group consisting of ball bonds, stitch bonds, stitch bonds on bonding pad, and stitch bonds on ball.

21. The method of Claim 17 further comprising connecting a first trace in the semiconductor die between bond pads of the pair of bond pads.

22. The method of Claim 17 further comprising locating a second bond pad of the at least one pair of bond pads in the internal portion of the semiconductor die.

23. The method of Claim 17 wherein the single corresponding bond wire is selected from the group consisting of power interconnects, ground interconnects, and signal interconnects.

24. The method of Claim 17 further comprising:
attaching a plurality of pairs of bond pads to the semiconductor die; and
connecting a corresponding wire between each of the pairs of bond pads such that each bond pad of the pairs of bond pads includes a single wire bond.